

# MC100LVEL31

## 3.3V ECL D Flip-Flop with Set and Reset

### Description

The MC100LVEL31 is a D flip-flop with set and reset. The device is functionally equivalent to the EL31 device but operates from a 3.3 V supply. With propagation delays and output transition times essentially equivalent to the EL31, the LVEL31 is ideally suited for those applications which require the ultimate in AC performance at low power supply voltages.

Both set and reset inputs are asynchronous, level triggered signals. Data enters the master portion of the flip-flop when clock is LOW and is transferred to the slave, and thus the outputs, upon a positive transition of the clock.

### Features

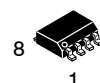
- 475 ps Typical Propagation Delay
- 2.9 GHz Toggle Frequency
- ESD Protection: >4 kV Human Body Model, >200 V Machine Model
- The 100 Series Contains Temperature Compensation
- PECL Mode Operating Range:  $V_{CC} = 3.0\text{ V}$  to  $3.8\text{ V}$  with  $V_{EE} = 0\text{ V}$
- NECL Mode Operating Range:  $V_{CC} = 0\text{ V}$  with  $V_{EE} = -3.0\text{ V}$  to  $-3.8\text{ V}$
- Internal Input Pulldown Resistors
- Meets or Exceeds JEDEC Spec EIA/JESD78 IC Latchup Test
- Moisture Sensitivity Level 1  
For Additional Information, see Application Note AND8003/D
- Flammability Rating: UL 94 V-0 @ 0.125 in, Oxygen Index: 28 to 34
- Transistor Count = 121 devices
- Pb-Free Packages are Available



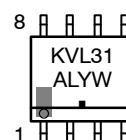
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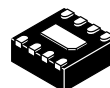
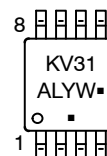
### MARKING DIAGRAMS\*



**SOIC-8**  
**D SUFFIX**  
**CASE 751**



**TSSOP-8**  
**DT SUFFIX**  
**CASE 948R**



**DFN8**  
**MN SUFFIX**  
**CASE 506AA**



A = Assembly Location  
L = Wafer Lot  
Y = Year  
W = Work Week  
M = Date Code  
▪ = Pb-Free Package

(Note: Microdot may be in either location)

\*For additional marking information, refer to Application Note AND8002/D.

### ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 5 of this data sheet.

# MC100LVEL31

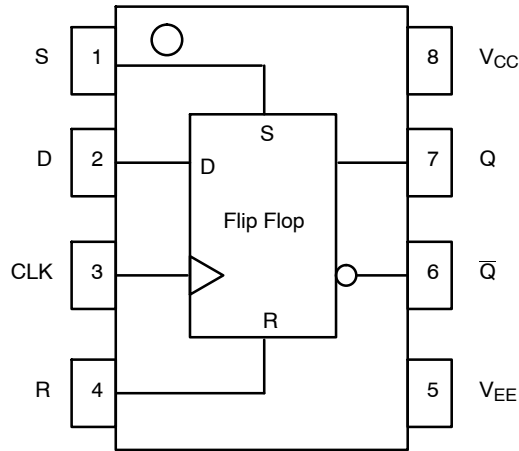


Figure 1. Logic Diagram and Pinout Assignment

Table 1. PIN DESCRIPTION

PIN	FUNCTION
CLK	ECL Clock Input
Q, $\bar{Q}$	ECL Differential Data Outputs
D	ECL Data Input
R	ECL Reset Input
S	ECL Set Input
V <sub>CC</sub>	Positive Supply
V <sub>EE</sub>	Negative Supply
EP	(DFN8 only) Thermal exposed pad must be connected to a sufficient thermal conduit. Electrically connect to the most negative supply (GND) or leave unconnected, floating open.

Table 2. TRUTH TABLE

D	S	R	CLK	Q	$\bar{Q}$
L	L	L	Z	L	H
H	L	L	Z	H	L
X	H	L	X	H	L
X	L	H	X	L	H
X	H	H	X	Undef	Undef

Z = LOW to HIGH Transition  
X = Don't Care

Table 3. MAXIMUM RATINGS

Symbol	Parameter	Condition 1	Condition 2	Rating	Unit
V <sub>CC</sub>	PECL Mode Power Supply	V <sub>EE</sub> = 0 V		8 to 0	V
V <sub>EE</sub>	NECL Mode Power Supply	V <sub>CC</sub> = 0 V		-8 to 0	V
V <sub>I</sub>	PECL Mode Input Voltage NECL Mode Input Voltage	V <sub>EE</sub> = 0 V V <sub>CC</sub> = 0 V	V <sub>I</sub> ≤ V <sub>CC</sub> V <sub>I</sub> ≥ V <sub>EE</sub>	6 to 0 -6 to 0	V V
I <sub>out</sub>	Output Current	Continuous Surge		50 100	mA mA
T <sub>A</sub>	Operating Temperature Range			-40 to +85	°C
T <sub>stg</sub>	Storage Temperature Range			-65 to +150	°C
θ <sub>JA</sub>	Thermal Resistance (Junction-to-Ambient)	0 lfpm 500 lfpm	8 SOIC 8 SOIC	190 130	°C/W °C/W
θ <sub>JC</sub>	Thermal Resistance (Junction-to-Case)	Standard Board	8 SOIC	41 to 44 ± 5%	°C/W
θ <sub>JA</sub>	Thermal Resistance (Junction-to-Ambient)	0 lfpm 500 lfpm	8 TSSOP 8 TSSOP	185 140	°C/W °C/W
θ <sub>JC</sub>	Thermal Resistance (Junction-to-Case)	Standard Board	8 TSSOP	41 to 44 ± 5%	°C/W
θ <sub>JA</sub>	Thermal Resistance (Junction-to-Ambient)	0 lfpm 500 lfpm	DFN8 DFN8	129 84	°C/W °C/W
T <sub>sol</sub>	Wave Solder Pb Pb-Free	<2 to 3 sec @ 248°C <2 to 3 sec @ 260°C		265 265	°C
θ <sub>JC</sub>	Thermal Resistance (Junction-to-Case)	(Note 1)	DFN8	35 to 40	°C/W

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. JEDEC standard multilayer board – 2S2P (2 signal, 2 power)

# MC100LEVEL31

**Table 4. LVPECL DC CHARACTERISTICS**  $V_{CC} = 3.3\text{ V}$ ;  $V_{EE} = 0.0\text{ V}$  (Note 1)

Symbol	Characteristic	-40°C			25°C			85°C			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
$I_{EE}$	Power Supply Current		30	35		30	35		32	38	mA
$V_{OH}$	Output HIGH Voltage (Note 3)	2215	2295	2420	2275	2345	2420	2275	2345	2420	mV
$V_{OL}$	Output LOW Voltage (Note 3)	1470	1605	1745	1490	1595	1680	1490	1595	1680	mV
$V_{IH}$	Input HIGH Voltage	2135		2420	2135		2420	2135		2420	mV
$V_{IL}$	Input LOW Voltage	1490		1825	1490		1825	1490		1825	mV
$I_{IH}$	Input HIGH Current			150			150			150	μA
$I_{IL}$	Input LOW Current	0.5			0.5			0.5			μA

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

2. Input and output parameters vary 1:1 with  $V_{CC}$ .  $V_{EE}$  can vary  $\pm 0.3\text{ V}$ .

3. Outputs are terminated through a  $50\ \Omega$  resistor to  $V_{CC} - 2.0\text{ V}$ .

**Table 5. LVNECL DC CHARACTERISTICS**  $V_{CC} = 0.0\text{ V}$ ;  $V_{EE} = -3.3\text{ V}$  (Note 1)

Symbol	Characteristic	-40°C			25°C			85°C			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
$I_{EE}$	Power Supply Current		30	35		30	35		32	38	mA
$V_{OH}$	Output HIGH Voltage (Note 5)	-1085	-1005	-880	-1025	-955	-880	-1025	-955	-880	mV
$V_{OL}$	Output LOW Voltage (Note 5)	-1830	-1695	-1555	-1810	-1705	-1620	-1810	-1705	-1620	mV
$V_{IH}$	Input HIGH Voltage	-1165		-880	-1165		-880	-1165		-880	mV
$V_{IL}$	Input LOW Voltage	-1810		-1475	-1810		-1475	-1810		-1475	mV
$I_{IH}$	Input HIGH Current			150			150			150	μA
$I_{IL}$	Input LOW Current	0.5			0.5			0.5			μA

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

4. Input and output parameters vary 1:1 with  $V_{CC}$ .  $V_{EE}$  can vary  $\pm 0.3\text{ V}$ .

5. Outputs are terminated through a  $50\ \Omega$  resistor to  $V_{CC} - 2.0\text{ V}$ .

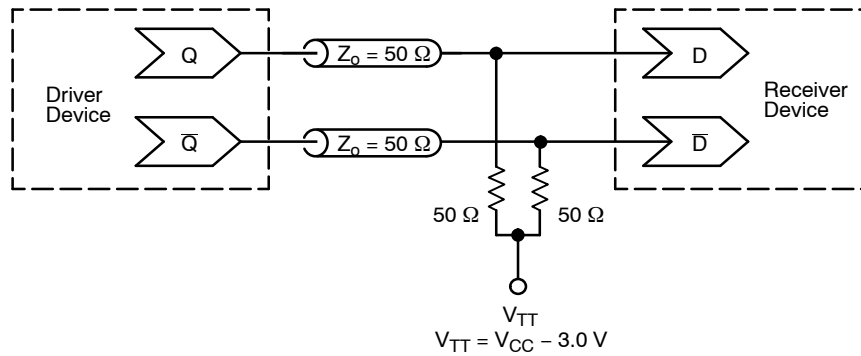
# MC100LVEL31

**Table 6. AC CHARACTERISTICS**  $V_{CC} = 3.3\text{ V}$ ;  $V_{EE} = 0.0\text{ V}$  or  $V_{CC} = 0.0\text{ V}$ ;  $V_{EE} = -3.3\text{ V}$  (Note 6)

Symbol	Characteristic	-40°C			25°C			85°C			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
$f_{\max}$	Maximum Toggle Frequency	2.7			2.9			2.9			GHz
$t_{PLH}$ $t_{PHL}$	Propagation Delay to Output CLK S, R	365 385	465 475	580 620	375 395	475 485	590 630	415 435	530 525	630 670	ps
$t_S$ $t_H$	Setup Time Hold Time	150 250	0 100		150 250	0 100		150 250	0 100		ps
$t_{RR}$	Set/Reset Recovery	400	200		400	200		400	200		ps
$t_{JITTER}$	Cycle-to-Cycle Jitter		TBD			TBD			TBD		ps
$t_{PW}$	Minimum Pulse Width CLK Set, Reset	340 600			340 600			340 600			ps
$t_r$ $t_f$	Output Rise/Fall Times Q (20% – 80%)	120	220	320	120	220	320	120	220	320	ps

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

6.  $V_{EE}$  can vary  $\pm 0.3\text{ V}$ .



**Figure 2. Typical Termination for Output Driver and Device Evaluation**  
(See Application Note AND8020/D – Termination of ECL Logic Devices.)

# MC100LVEL31

## ORDERING INFORMATION

Device	Package	Shipping <sup>†</sup>
MC100LVEL31D	SOIC-8	98 Units / Rail
MC100LVEL31DG	SOIC-8 (Pb-Free)	98 Units / Rail
MC100LVEL31DR2	SOIC-8	2500 / Tape & Reel
MC100LVEL31DR2G	SOIC-8 (Pb-Free)	2500 / Tape & Reel
MC100LVEL31DT	TSSOP-8	100 Units / Rail
MC100LVEL31DTG	TSSOP-8 (Pb-Free)	100 Units / Rail
MC100LVEL31DTR2	TSSOP-8	2500 / Tape & Reel
MC100LVEL31DTR2G	TSSOP-8 (Pb-Free)	2500 / Tape & Reel
MC100LVEL31MNR4	DFN8	1000 / Tape & Reel
MC100LVEL31MNR4G	DFN8 (Pb-Free)	1000 / Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

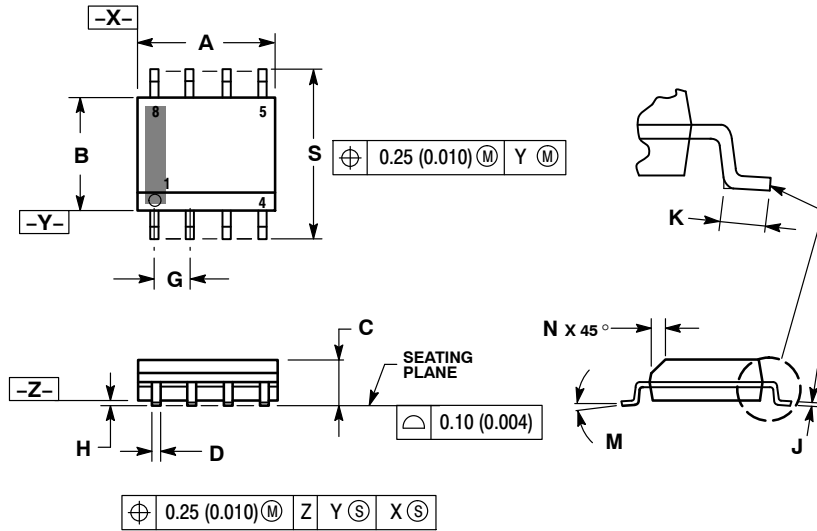
## Resource Reference of Application Notes

- AN1405/D** – ECL Clock Distribution Techniques
- AN1406/D** – Designing with PECL (ECL at +5.0 V)
- AN1503/D** – ECLinPS™ I/O SPICE Modeling Kit
- AN1504/D** – Metastability and the ECLinPS Family
- AN1568/D** – Interfacing Between LVDS and ECL
- AN1672/D** – The ECL Translator Guide
- AND8001/D** – Odd Number Counters Design
- AND8002/D** – Marking and Date Codes
- AND8020/D** – Termination of ECL Logic Devices
- AND8066/D** – Interfacing with ECLinPS
- AND8090/D** – AC Characteristics of ECL Devices

# MC100LVEL31

## PACKAGE DIMENSIONS

SOIC-8 NB  
CASE 751-07  
ISSUE AH

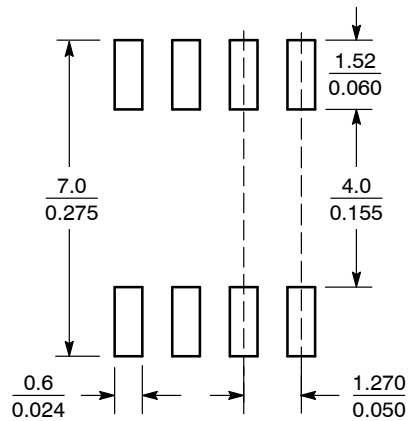


### NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION A AND B DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.
6. 751-01 THRU 751-06 ARE OBSOLETE. NEW STANDARD IS 751-07.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.80	5.00	0.189	0.197
B	3.80	4.00	0.150	0.157
C	1.35	1.75	0.053	0.069
D	0.33	0.51	0.013	0.020
G	1.27 BSC		0.050 BSC	
H	0.10	0.25	0.004	0.010
J	0.19	0.25	0.007	0.010
K	0.40	1.27	0.016	0.050
M	0 °	8 °	0 °	8 °
N	0.25	0.50	0.010	0.020
S	5.80	6.20	0.228	0.244

## SOLDERING FOOTPRINT\*



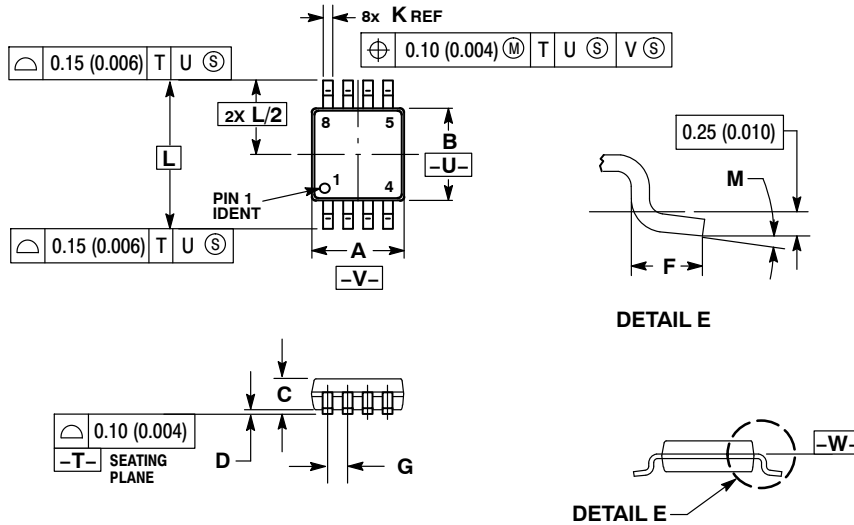
SCALE 6:1 (mm/inches)

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

# MC100LVEL31

## PACKAGE DIMENSIONS

**TSSOP-8**  
**DT SUFFIX**  
 PLASTIC TSSOP PACKAGE  
 CASE 948R-02  
 ISSUE A



### NOTES:

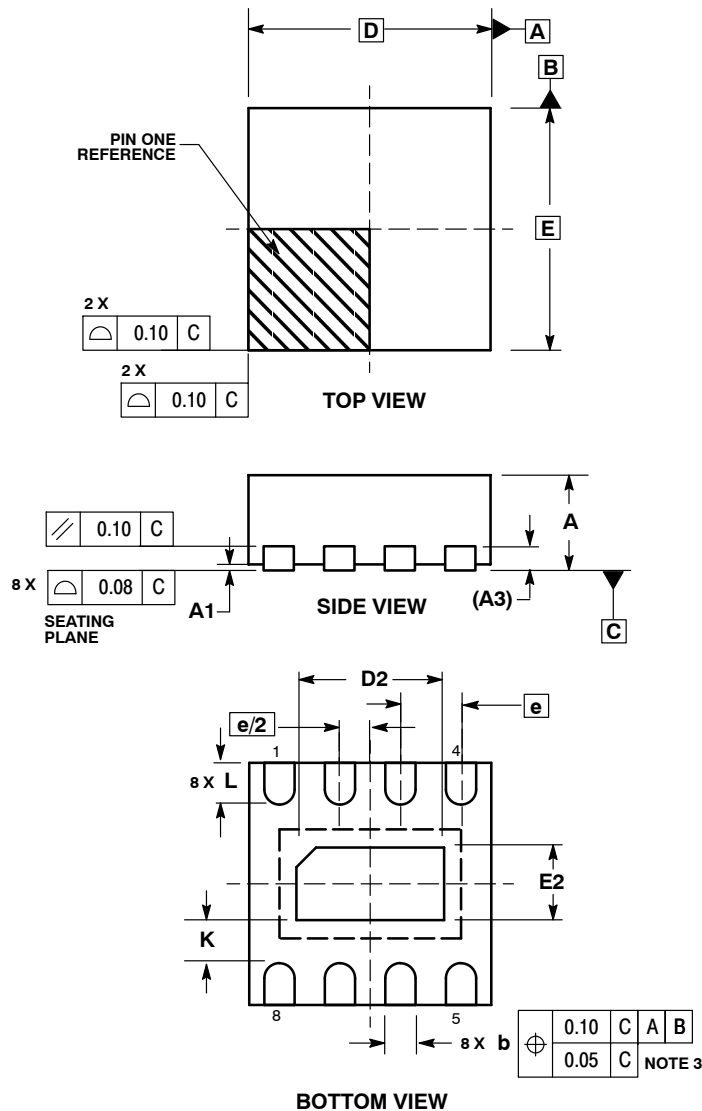
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION A DOES NOT INCLUDE MOLD FLASH. PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
5. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
6. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	2.90	3.10	0.114	0.122
B	2.90	3.10	0.114	0.122
C	0.80	1.10	0.031	0.043
D	0.05	0.15	0.002	0.006
F	0.40	0.70	0.016	0.028
G	0.65 BSC		0.026 BSC	
K	0.25	0.40	0.010	0.016
L	4.90 BSC		0.193 BSC	
M	0°	6°	0°	6°

# MC100LVEL31

## PACKAGE DIMENSIONS

DFN8  
CASE 506AA-01  
ISSUE D




### NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994 .
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.25 AND 0.30 MM FROM TERMINAL.
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

MILLIMETERS		
DIM	MIN	MAX
A	0.80	1.00
A1	0.00	0.05
A3	0.20	REF
b	0.20	0.30
D	2.00	BSC
D2	1.10	1.30
E	2.00	BSC
E2	0.70	0.90
e	0.50	BSC
K	0.20	---
L	0.25	0.35

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